1	
\searrow	
Ż	
2	
(,)	

	01-10-2006
Form PTO-1595	
Rev. 03/01) DMB No. 0651-0027 (exp. 5/31/200	

HEET

U.S. DEPARTMENT OF COMMERCE
U.S. Patent and Trademark Office

OMB No. 0651-0027 (exp. 5/31/200				
Tab settings	92 → → ₽ ₀			
To the Honorable Commissioner of Patents and Trademarks: F	Please Record the attached original documents or copy thereof.			
Name of conveying party(ies):	2. Name and address of receiving party(ies) Name: Hynix Semiconductor Inc.			
Hong Goo Lee	Name: Hynix Semiconductor Inc.			
Additional name of conveying party(ies) attached? ☐ Yes ☒ No	Internal			
3. Nature of conveyance:	Street Address: San 136-1, Ami-ri, Bubal-eup,			
	Icheon-si, Gyeonggi-do 467-701, KOREA			
☐ Security Agreement ☐ Change of Name				
☐ Other	City: State: Zip:			
Execution Dates: December 23, 2005	Additional Name(s) & address(es) attached? ☐ Yes ☒ No			
	n, the execution data of the application is: December 23, 2005			
Name and address of party to whom correspondence concerning this document should be mailed:	6. Total number of applications and patents involved: 1			
Name: Johnny A. Kumar	7. Total fee (37 CFR 3.41) \$ 40.00			
Internal Address: Heller Ehrman LLP	☑ Enclosed			
	Authorized to be charged to deposit account			
Street Address: 1717 Rhode Island Avenue, N.W.	8. Deposit account number: 08-1641			
City: Washington State: D.C. Zip: 20036	(Attach duplicate copy of this page if paying by deposit account)			
DO NOT USE THIS SPACE				
9. Statement and signature. To the best of my knowledge and belief, the foregoing informis a true copy of the original document. Johnny A. Kumar Name of Person Signing	0.17			
Total number of pages including cover sheet, attachments, and documents: 3				

01/04/2006 SSITHIB1 00000008 11321539 01 FC:8021 40.00 OP

Attorney Docket No.:

ASSIGNMENT AND AGREEMENT

WHEREAS, [Hong Goo LEE] (hereinafter referred to singly and collectively as "ASSIGNOR") have invented a certain invention entitled [METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE] for which an application for United States Letters Patent is filed concurrently herewith;

WHEREAS, [Hynix Semiconductor Inc.], having its principal place of business at [San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do 467-701, Korea] (hereinafter referred to as "ASSIGNEE") is desirous of acquiring the entire interest therein;

NOW THEREFORE, in view of good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, ASSIGNOR has sold, assigned, and transferred, and by these presents hereby sells, assigns, and transfers, unto ASSIGNEE, its successors and assigns, the full and exclusive right, title, and interest in and to (a) the above-identified invention or inventions and all improvements and modifications thereof, (b) the above-identified application and all other applications for Letters Patent of the United States and countries foreign thereto for the above-identified invention or inventions and all improvements and modifications thereof, (c) all Letters Patent which may issue from said applications in the United States and countries foreign thereto, (d) all divisions, continuations, reissues, and extensions of said applications and Letters Patent, and (e) the right to claim for any of said applications the full benefits and priority rights under the International Convention and any other international agreement to which the United States adheres; such right, title, and interest to be held and enjoyed by ASSIGNEE, its successors and assigns, to the full end of the term or terms for which any and all such Letters Patent may be granted as fully and entirely as would have been held and enjoyed by ASSIGNOR had this Assignment not been made.

ASSIGNOR HEREBY AUTHORIZES AND REQUESTS the Commissioner of Patents and Trademarks to issue said Letters Patent to ASSIGNEE as assignee of the entire interest, for the sole use and benefit of ASSIGNEE, its successors and assigns.

ASSIGNOR HEREBY AGREES (a) to communicate to ASSIGNEE, its successors and assigns, or their representatives or agents, all facts and information known or available to ASSIGNOR respecting said invention or inventions, improvements, and modifications including evidence for interference, reexamination, reissue, opposition, revocation, extension, or infringement purposes or other legal, judicial, or administrative proceedings, whenever requested by ASSIGNEE; (b) to testify in person or by affidavit as required by ASSIGNEE, its successors and assigns, in any such proceeding in the United States or a country foreign thereto; (c) to execute and deliver, upon request by ASSIGNEE, all lawful papers including, but not limited to, original, divisional, continuation, and reissue applications, renewals, assignments, powers of attorney, oaths, affidavits, declarations, depositions; and (d) to provide all reasonable assistance to ASSIGNEE, its successors and assigns, in obtaining and enforcing proper title in and protection for said invention or inventions, improvements, and modifications under the intellectual property laws of the United States and countries foreign thereto.

ASSIGNOR HEREBY REPRESENTS AND WARRANTS that ASSIGNOR has the full and unencumbered right to sell, assign, and transfer the interests sold, assigned, and

Page 1 of 2

Attorney Docket No.:

transferred herein, and that ASSIGNOR has not executed and will not execute any document or instrument in conflict herewith.

ASSIGNOR HEREBY GRANTS to the law firm of **Heller Ehrman White & McAuliffe** the power and authority to insert in this Assignment any further identification which may be necessary or desirable to comply with the rules of the U.S. Patent and Trademark Office for recordation of this Assignment.

ASSIGNOR UNDERSTANDS AND AGREES that the attorneys and agents of the law firm of Heller Ehrman White & McAuliffe do not personally represent ASSIGNOR or ASSIGNOR's legal interests, but instead represent the interests of ASSIGNEE; since said attorneys and agents cannot provide legal advice to ASSIGNOR with respect to this Assignment, ASSIGNOR acknowledges its right to seek its own independent legal counsel.

NAMES AND SIGNATURES OF INVENTORS				
Name: Hong Goo LEE	Signature: Hing two . Lee	Date: Pecember 27,2005		
Name:	Signature:	Date:		
Name:	Signature:	Date:		
NAMES AND SIGNATURES OF WITNESSES				
Name: Hae Jin KIM	Signature: Hae	Date: December 23,20.5		
Name:	Signature:	Date:		
Name:	Signature:	Date:		

Page 2 of 2

PATENT REEL: 018530 FRAME: 0198